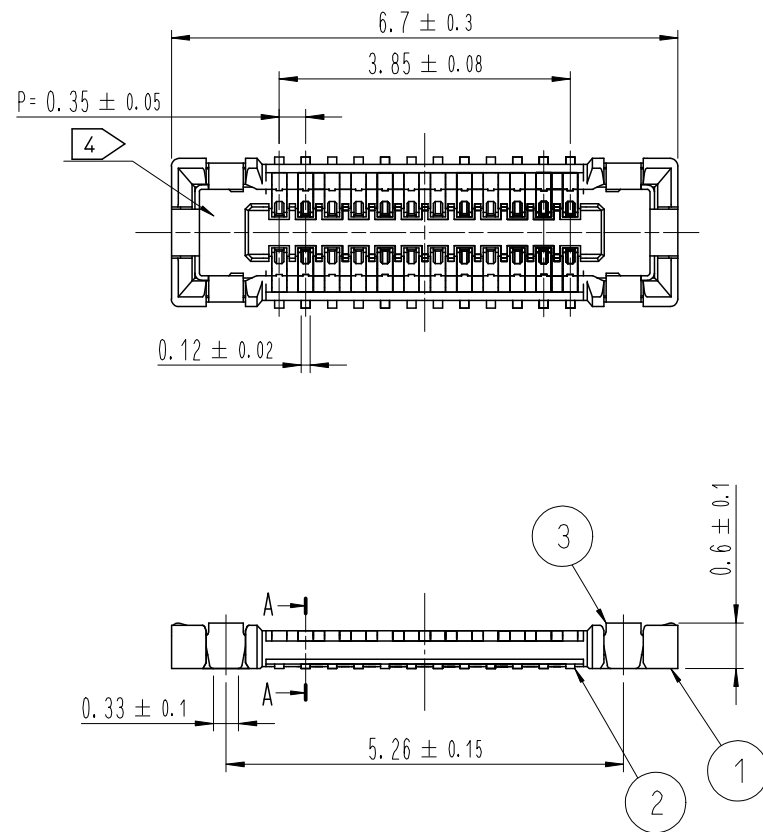


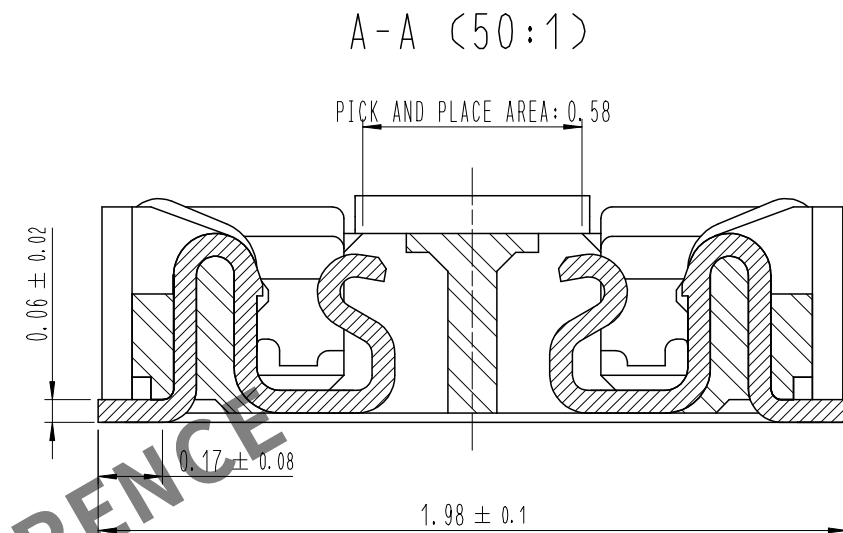
Apr.1.2024 Copyright 2024 HIROSE ELECTRIC CO., LTD. All Rights Reserved.
In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.



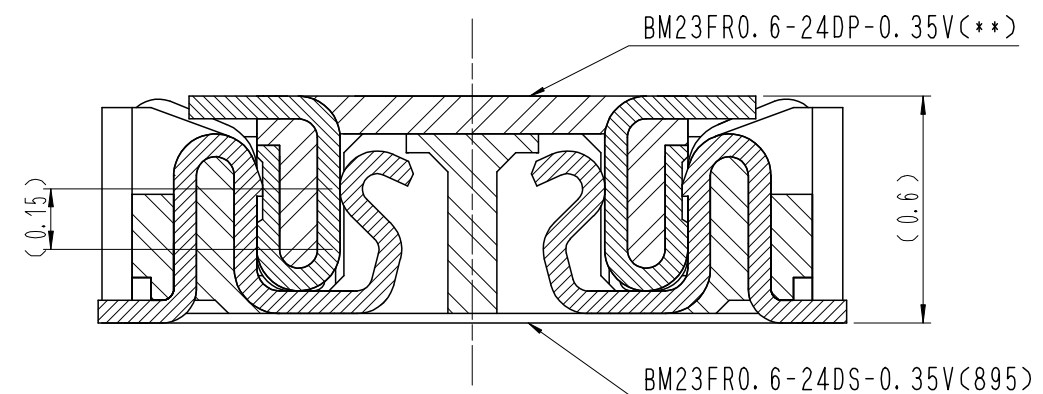
DRAWING FOR REFERENCE
This is subject to change without notice

- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
 - 2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD $0.05 \mu\text{m}$ MIN.
SMT LEAD : GOLD $0.05 \mu\text{m}$ MIN.
UNDERPLATING : NICKEL $1 \mu\text{m}$ MIN.
(SURFACE : SEALING)
 - 3. METAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD $0.05 \mu\text{m}$ MIN.
UNDERPLATING : NICKEL $1 \mu\text{m}$ MIN.
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.

	COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE		COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE
△						. . .	△						. . .
△						. . .	△						. . .
△						. . .	△						. . .

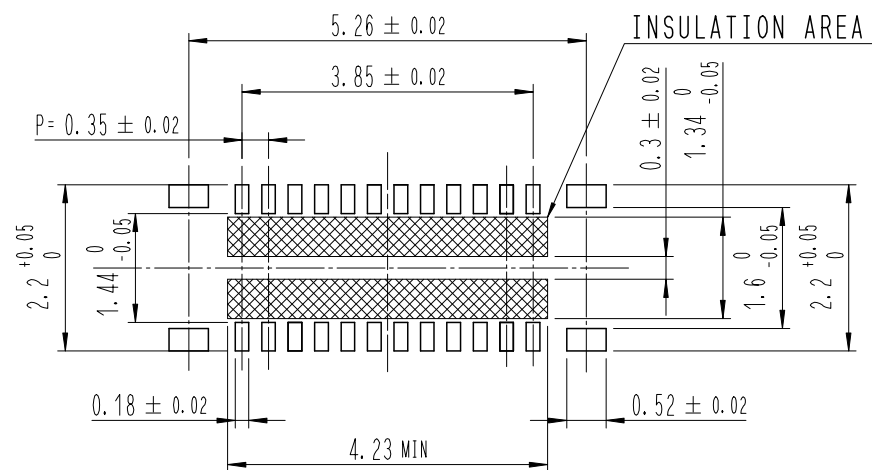


ENGAGEMENT FIGURE (50:1)

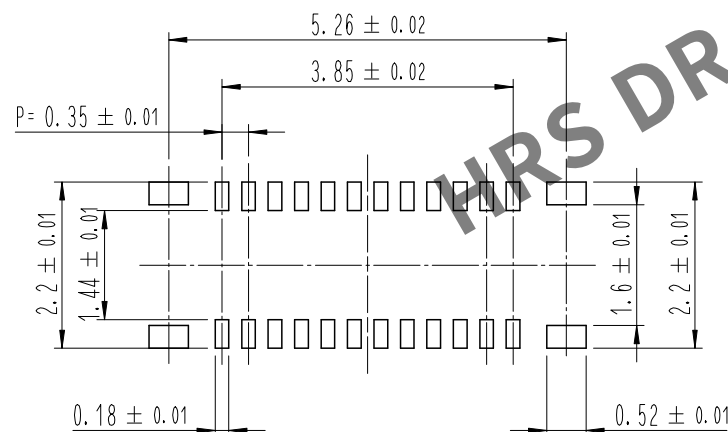


4	PS	CLEAR (EMBOSSED CARRIER TAPE)		7	PS	CLEAR (REINFORCEMENT COLLAR)
3	COPPER ALLOY	3		6	PS	BLACK (PLASTIC REEL)
2	COPPER ALLOY	2		5	POLYESTER	CLEAR (COVER TAPE)
1	LCP	UL94 V-0, BLACK				
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS	
REMARKS				DRAWN	DESIGNED	CHECKED
				S. H. JUNG	S. H. JUNG	H. W. JO
				17. 05. 08	17. 05. 08	17. 05. 08
					APPROVED	RELEASED
					T. S. KANG	17. 05. 08
CODE NO. (OLD)	SCALE	DRAWING NO.	PART NO.			
	10:1	EDC3-631806	BM23FR0.6-24DS-0.35V(895)			
	UNITS	HRS HIROSE KOREA CO., LTD.	CODE NO			
	mm		CL 6644-0003-2-895			

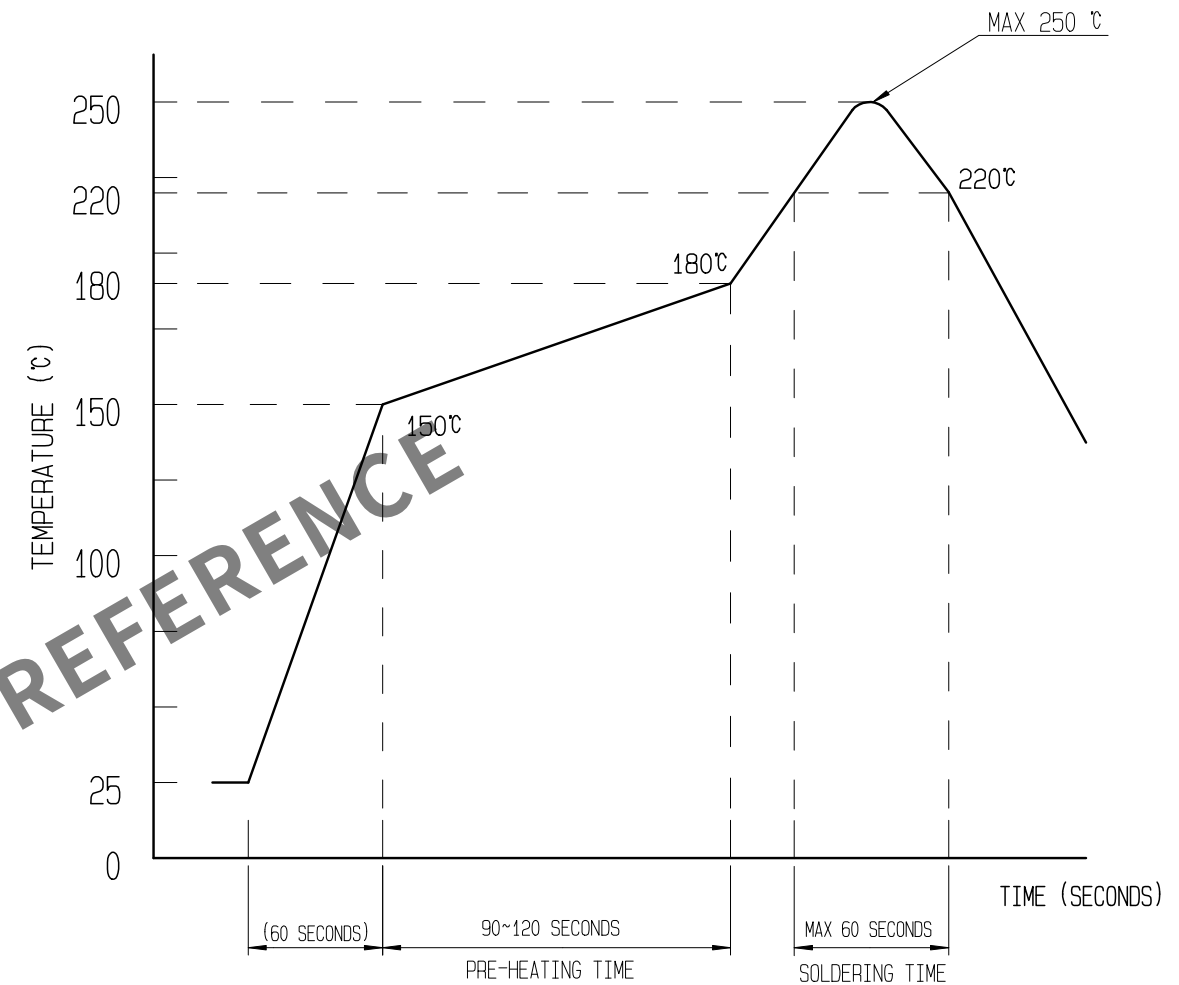
6 RECOMMENDED PCB LAYOUT



RECOMMENDED METAL MASK DIMENSIONS
MATAL MASK THICKNESS : $100 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N2 REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
1) REFLOW TIME
DURATION ABOVE 220°C : 60 SEC MAX.
(PEAK TEMPERATURE: 250°C MAX)
2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

5. THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
6. PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-631806	PART NO.	BM23FR0.6-24DS-0.35V(895)	
	SCALE	10:1	CODE NO	CL 6644-0003-2-895	2/3
	UNITS	mm	HIROSE KOREA CO., LTD.		

